

Plans and developments for Cherenkov PID upgrade for ALICE 3

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Outline



- Introduction to ALICE 3 and PID requirements
- RICH layout and performance studies in Geant4
- R&D topics
- Plans

ALICE 3: phase IIb upgrade for LHC Run 5 & 6



Key physics questions and drivers

- precision measurements of dileptons
 - evolution of the quark gluon plasma
 - mechanisms of chiral symmetry restoration in the quark-gluon plasma
- systematic measurements of (multi-)heavy-flavoured hadrons
 - transport properties in the quark-gluon plasma
 - mechanisms of hadronisation from the quark-gluon plasma

• hadron correlations

- interaction potentials
- fluctuations

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...



Heavy-ion collisions at the LHC are ideal to address these questions, but require improved detector performance and statistics.



CERN-LHCC-2022-009

The ALICE3 detector



- High-efficiency for heavy-quark identification and reconstruction of low-mass dielectrons
- Compact all-silicon tracker with unprecedently low material budget, with retractable vertex detector (tracking precision x 3: $10\mu m$ at $p_T = 200$ MeV)
- Large acceptance with excellent coverage down to low p_{T} (acceptance x 4.5: $|\eta| < 4$)
- Extensive particle ID
- Superconducting magnet system
- Continuous readout and online processing (A-A rate x 5, pp x 25)





innovative technologies relevant for future HEP experiments

ALICE Phase IIb Upgrade Timeline





- 2023 2025: selection of technologies, small-scale proof of concept prototypes (~25% of R&D funds)
- 2026 2027: large-scale engineered prototypes (~75% of R&D funds)
 Technical
 Design Reports
- 2028 2030: construction and testing
- . 2031 2032: contingency
- 2033 2034: installation and commissioning
- 2035 2042: physics campaign



ALICE 3 charged PID system



• R = 0.19 (0.85) m

Forward TOF Ecal (FCT) side:

- $+1.75(-4.0) \le \eta \le +4.0(-1.75)$
- Z = +4.05 (-4.05) m
- R = 0.15 (0.15) 1.5 (1.5) m

- L = 5.6 m
- R = 0.90-1.12 m

Forward RICH Ecal (FCT) side:

- $+1.75(-3.0) \le \eta \le +4.0(-1.75)$
- Z = +4.10 (-4.10) m
- R = 0.15 (0.5) 1.5 (1.5) m

- R = 2.8 m

ALICE 3 charged PID requirements



Component	Observables	Barrel ($ \eta < 1.75$)	Forward(1.75< $ \eta $ < 4)	Detectors
Hadron ID	(Multi-)charm baryons	π/K/p up to ~10 GeV/c		• TOF: $\sigma_{TOF} \sim 20 \text{ ps}$ • bRICH: n=1.03, σ_{θ} ~ 1.5 mrad • fRICH: n=1.006- 1.03, $\sigma_{\theta} \sim 1.5$ mrad
Electron ID	Dielectrons, quarkonia, X _{c1} (3872)	π rejection by 1000x up to 2-3 GeV/c		 TOF: σ_{TOF} ~ 20 ps bRICH: n=1.03, σ_θ ~ 1.5 mrad
Muon ID	Quarkonia, X _{c1} (3872)	Muons from $p_{\rm T} \sim 1.5$ GeV/c at η =0		Steel absorber: L ~ 70 cm, muon detector (scintillators)

RICH systems in the LoI: motivations



Extend electron and charged hadron ID at p higher than the TOF range, e.g in the barrel: e/π : 0.5 - 2 GeV/c π/K : 2.0 - 10.0 GeV/c K/p: 4.0 - 16.0 GeV/c



- Barrel RICH: aerogel radiator (2cm, n=1.03)
 + 20 cm expansion gap + SiPM photodetector
- Forward RICH: idem, but lower n



Results from "fast" parametric simulation, assuming a Cherenkov angle resolution at saturation of 1.5 mrad

Aerogel Cherenkov radiator



Cherenkov relation

momentum threshold for Cherenkov emission

$$\cos \vartheta_c = \frac{1}{n\beta} \rightarrow \beta_{th} = \frac{1}{n} \rightarrow p_{th} = \frac{m}{\sqrt{n^2 - 1}}$$

aerogel n	βth	momentum threshold [GeV/c]				
		е	μ	π	К	р
1.01	0.99009901	0.0036	0.7453	0.9845	3.4821	6.6181
1.02	0.98039216	0.0025	0.5257	0.6944	2.4561	4.6681
1.03	0.97087379	0.0021	0.4281	0.5656	2.0005	3.8021
1.04	0.96153846	0.0018	0.3699	0.4886	1.7282	3.2846
1.05	0.95238095	0.0016	0.3300	0.4359	1.5420	2.9307
1.06	0.94339623	0.0015	0.3005	0.3970	1.4042	2.6688
1.07	0.93457944	0.0013	0.2776	0.3667	1.2969	2.4649
1.08	0.92592593	0.0013	0.2590	0.3421	1.2102	2.3001
1.09	0.91743119	0.0012	0.2436	0.3218	1.1383	2.1634
1.14	0.87719298	0.0009	0.1930	0.2550	0.9019	1.7142

Hydrophobic silica aerogel from Aerogel Factory Co. Ltd (Chiba, Japan):

- No degradation for exposure to humidity, easy storage
- Excellent transparency in the range 1.02-1.05
- Stable up to 10 Mrad

- Best match with PID requirements, large choice of refractive indexes
- > Possibility to fine tune PID threshold and range





Barrel RICH layout options



Proxmity focusing layout:

- Single radiator layer
- Cylindrical geometry



\rightarrow con's:

 Angular resolution dominated by geometrical aberration

Aerogel focusing layout:

 Two or more aerogel layers with increasing refractive index



\rightarrow pro's:

 Photons produced in the second layer reach the pd @ same radius as the first one, thus reducing the geometric aberration error at saturation

\rightarrow con's:

• Fine tuning of focusing layer indices vs track inclination must be taken into account

Mirror focusing layout:

- Spheric/parabolic mirrors
- Projective geometry



→ pro's:

- Reduce/suppress geometric aberration
- Reduce p.d. area

\rightarrow con's:

- ~ 30% photon loss due to double crossing of aerogel and mirror reflection
- spherical aberration and mirror alignment to be taken into account

The photon detector



Main requirements

- Single photon sensitivity in the visible range (Photon Detection Efficiency (PDE) > 40-50%)
- Integration fill factor > 90%
- Pixel ~ 3x3 mm² (down to 1x1 mm²)
- Time resolution σ < ~ 100 ps
- Magnetic field: up to 2 T
- Expected radiation load: NIEL ~ 10¹² 1 MeV n_{eq} /cm²

Vacuum-based devices (MCPs, LAPPDs)

- Single photon detection efficiency ~ 25-30%
- Low noise and good radiation tolerance
- Time resolution ~ 30 ps
- Main limitations:
 - Sensitivity to B (x10 gain drop above 0.5 T, no gain for \perp B)
 - HV operation
 - Bulky, reduced fill factor ~ 70%, large X0
 - Cost

SiPM

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- PDE ~ 50%
- LV operation
- Time resolution ~ 50 ps
- Main limitations:
 - Noise at room T, increase above 10^{10} MeV n_{eq} /cm²
 - Cost (but lower than vacuum-based)

The photon detector



(Typ. Ta=25 °C)

Example: SiPM HPK 13360 3050CS

- \circ 3x3 mm² pixel (microcell of 3600 SPADs with 50 μ m pitch)
- Dark count rate (DCR) ~ 50 kHz/mm²
- 50 ps time resolution (RMS)



overvoltage [V]

Main requirements

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- Pixel ~ 3x3 mm² (down to 1x1 mm²)
- Time resolution σ < ~ 100 ps
- Magnetic field: up to 2 T
- Expected radiation load: NIEL ~ 10¹² 1 MeV n_{eq} /cm²



Proximity focusing studies summary



Detector parameters for Geant4

- R = 0.90-1.12 m, |Δz|<2.8 m
- 37(z) x 36 (r φ) tiles: Radiator: 15 cm x 15 cm SiPM layer: 15 cm x 19 cm
- Aerogel: T = 2 cm, n = 1.03 @ 400 nm
- SiPM pixel size: 3 x 3 mm²
- <u>Photosensitive area</u>: **38 m²**





Performance η dependence, for very inclined tracks:

- geometric aberration increase
- photon losses







Proximity focusing studies summary



Performance in central Pb-Pb collisions



Selection cuts

- Timing (2σ cut)
- Hough transform cut (N_{ph,min} variable with track sector)



Mirror focusing studies summary



Detector parameters

- **Projective layout** with hermeticity to tracks
- Variable mirror radius to keep $\Delta R = 22$ cm for all sectors
- 36 sectors in $r\phi$, 21 sectors in Z
- 3x3 and 1x1 mm pixels
- <u>Photosensitive area</u>: **18.5 m²**







Mirror focusing studies summary





Mirror layout, **3x3 mm2** cells

Mirror layout, **1x1 mm2** cells



Similar to proximity focusing due to lower photon detection

Better performance by pixel error reduction (dominant)

Proximity focusing TOF+RICH – Projective



Detector parameters

- **Projective layout** with hermeticity to tracks
- Use TOF volume and increase proximity gap to 25 cm
- 1mm SiO₂ window coupled to SiPMs for TOF
- · 36 modules in r ϕ , 21 sectors in Z
- <u>Photosensitive area</u>: **25.7 m**²





TOF measurement in RICH SiPMs



Layout option under study:

- Reduction of costs and material budget, two PID techniques in one device
- Performance improvement both for TOF (increase of lever arm: 0.85 -> 1.1 m) and RICH (increase of proximity gap: 20 -> 25 cm)







Proximity focusing TOF+RICH – Projective





1x1 mm2 cells, 50 ps SPTR

e-PID range extension



NUCLEAR INSTRUMENTS A METHODS IN NOTICS RESEARCH

Goal

• Extend electron identification above 4 GeV/c Required for physics channels involving e.g. $J/\psi \rightarrow e^+e^-$

Strategy

- Implement gaseous radiator having $n \approx 1.0006$
- Gaseous radiators having large GWP (CF4, C4F10, ...) must be avoided
- E.g.: SLD CRID approach on a $C_5F_{10}O + N_2$ mixture
- From molar frac.s $w_{1,2}$ to n of a gas mixture: $n_{mix} = w_1 n_1 + w_2 n_2$
- $n_{mix} = 1.0006 \Rightarrow w_{C5F100} = 20\%$, $w_{N2} = 80\%$

ECal-less scenario

- Barrel ECal radial dimensions in the LoI: 1.15-1.45 m
- Possibility to increase the RICH proximity gap to 30-35 cm (and reduce magnet radius from 1.50 m to ≈1.35 m !!!)



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Abstract

We have developed an inexpensive sonar-based instrument to provide a routine online monitor of the composition and stability of several gas mixtures having application in a Cherenkov Ring Imaging Detector. The instrument is capable of detecting small (<1%) fluctuations in the relative concentration of the constituent gases and, in contrast with some other gas analysis techniques, lends itself well to complete automation.

e-PID range extension



21

Cherenkov emission threshold in GeV/c



e-PID range extension



Pb-Pb central collisons

Projective Layout (ΔR = 35 cm): 2 cm Aerogel (1.03) + Gas (1.0006) + 1 mm SiO₂ window (1.47) + 0.45 mm Epoxy resin (1.55)

Aerogel information

- Hit timing cut: $2\sigma_t$ matching with track
- Hough transfrom cut: $N_{\text{ph,min}} \ge 12$
- PID Above C.kov threshold: $3\sigma_{\theta}$ cut

Aerogel + Gas information

- Hit timing cut: $2\sigma_t$ matching with track
- Hough transfrom cut: $N_{\text{ph,min}} \ge 12$
- PID Above C.kov threshold: $3\sigma_{\theta}$ cut
- e^{\pm} hyp. accepted $\Leftrightarrow N(d_{min}^* < d < d_{max}) \ge 7$

Aerogel + Gas + TOF window information

- Hit timing cut: $2\sigma_t$ matching with track
- Hough transfrom cut: $N_{\text{ph,min}} \ge 12$
- PID Above C.kov threshold: $(3\sigma_{\theta} \text{ cut } \& 3\sigma_t) \text{ cut}$
- e^{\pm} hyp. accepted $\Leftrightarrow N(d_{min}^* < d < d_{max}) \ge 7$



*The minimum distance **d**_{min} allows to exclude the hits due to photons from the TOF window which are present for all particle species

Photons timing





R&D topics



• Aerogel

Aerogel specs: hydrophobic, T> 80% @ 400 nm, 15 x 15 cm²

- Optical properties (n and T homogeneity and reproducibility)
- Tile size (up to 20x20 cm²) and shape
- Multi-layer focusing (also monolithic?)

• Photodetection

SiPM specs: Pixel 1x1 mm², die (SiPM array) size ~ 1x1 cm², PDE > 40% at 450 nm, DCR < 50 kHz/mm², radiation hardness: NIEL ~ 10¹⁰ 1 MeV n_{eq}/cm², time resolution < 100 ps, packaging fill factor > 90% (TSV interconnection)

- Explore path towards monolithic (2D or 3D) SiPM in CMOS Imaging Sensor technology (massive R&D in industry on digital SPADs for consumer applications and automotive), to reduce costs, <u>customize</u> <u>sensor and improve performance</u>:
- MIP detection by thin radiator window for TOF
- Module concept and cooling integration

Ongoing R&D: aerogel characterization



#	Sample	n
1	LEC4-1b	1.03
2	LEC4-2a	1.03
3	LEC6-1a	1.03
4	LEC6-1b	1.03
5	LEC6-2b	1.03
6	SP3-0	1.03
7	SP3-1	1.03
8	LEC11-6	1.04
9	LEC11-7	1.04
10	LEC12-1	1.04
11	LEC12-4	1.04
12	LEC12-6	1.04
13	LEC8-1	1.05
14	LEC8-2	1.05
15	LEC8-6	1.05
16	LEC9-1	1.05
17	LEC9-2	1.05
18	TSA41-2a	1.00539
19	TSA41-2b	1.00544
20	TSA41-3a	1.00548
21	TSA38-2	1.0312
22	TSA38-8	1.0311

- 22 samples available from Aerogel Factory LTD, Chiba, JP ٠ (purchased with LHCb)
- Four n: 1.005, 1.03, 1.04, 1.05 ۲
- Two sizes: 11x11 cm² and 15x15 cm²
- Measurement of transaparency and uniformity
- Dimensional/shape characterization ٠







T mapping

Ongoing R&D: aerogel characterization



- Thickness variation: no impact on performance
- Planarity defect:
 - Can be included in Cherenkov angle reconstruction
 - According to supplier, there is margin for improvement

Ongoing R&D: prototype @ testbeam PS/T10





Ongoing R&D: prototype @ testbeam PS/T10





FEB 252

Detector parameters

- Radiator: T_r = 2 cm, n = 1.03-1.04
- Proximity gap: T_g=23.4 cm, Ar
- SiPM cooling: $-12^{\circ} < T < -5^{\circ}$
- $V_{ov,matrix} = 4.4 V, V_{ov,strips} = 6.9 V$





DAQ and Front-End Board (FEB)





Ongoing R&D: prototype @ testbeam PS/T10



N.B.: Excess with respect to full barrel sim. due to larger strip SiPM PDE

Time resolution measurements





3 mm thick NaF radiator (n = 1.3319 @ 400 nm), 4 mm apart from the central matrix

Limitation

No reference time available ⇒ Times referred to the cluster mean time

Test beam results

Measured mean number of clustered SiPMs : $N_{NaF} \approx 11-12$ Measured single SiPM time resolution: $\sigma_{SiPM} \approx 160 \ ps$ Extrapolated mean cluster time resolution: $\sigma_{\langle t \rangle} = \frac{\sigma_{SiPM}}{\sqrt{N_{NaF}}} \approx 47 \ ps$

There is room for improvement

Further investigations are being carried out for improving timing results: offsets and slewing corrections, thresholds for data acquisition, ASIC syncronization, etc.

SiPM R&D





- The access to customized SiPM opens the possibility of developing innovative technologies and detector applications
- Some key topics:
 - Single cell access (for screamer SPADs disabling and DCR reduction), active quenching (to improve fill factor and timing)
 - PDE improvement by: E-field engineering, A/R coating , max fill factor (BSI or microlenses)
 - DCR reduction by: E-field engineering, operation at lower V_{OV} if large enough PDE, cooling integration
 - Radiation hardness: cell layout, cooling/annealing
 - Timing performance, precise event time stamping for online and offline filtering (also wrt DCR): cell layout



FBK NUV-HD technology



SiPM packaging



- Module size ~ 20.4x20.4 cm² (0.02 cm spacing between dies,) -> fill factor > 99%
- Area to be covered: ~ 30 m² -> ~ 750 modules (950 assuming 80% yield), 380000 SiPM dies (630000 SiPM dies assuming 60% yield)
- Packaging options:
 - 2D (monolithic digital SiPM, <u>SPAD fill factor</u>? PDE? DCR? RH?)
 - 2.5D (using silicon interposer or PCB)
 - 3D (wafer to wafer bonding, requires further assembly on PCB)
- Cooling/annealing circuit embedding in PCB or silicon interposer (linked to DCR and radiation hardness)



ALICE

Direct detection of charged particles with SiPM

At the passage of a single charged particle → very high number of SPADs fire https://dx.doi.org/10.1088/1748-0221/17/06/P06007

Effect (due to **Cherenkov light** produced in the protection layers https://doi.org/10.48550/arXiv.2210.13244

As a consequence:

- Higher efficiency (wrt what expected from simple Fill Factor, FF)
- And also time resolutions around/below 30 ps

Further step: exploit SiPM for TOF measurements by detection of Cherenkov photons produced in a thin window



Anti-reflective coating



SiPM Anti Reflective Coating

Reflection effects

- Fresnel reflection between window and resin or resin and Silicon + total reflection between window and Ar
- Loss of photons from aerogel (accounted in the PDE)
- A larger PDE could be achieved by limiting reflection effects

Solutions:

- Conventional single-layer antireflection coating (ARC)
- (Multi-layer) ARC: double-layer ARC and triple-layer ARC
- Textured Si surface with upright random nano/micro pyramids formed by anisotropic etching.

Additional benefits:

- \cdot The PDE increase allows operation at lower V_{ov} hence lowerd DCR
- Limitation of crosstalk from reflection at Si interface of Cherenkov photons produced inside TOF window



Single-layer ARC

Double-layer ARC

Triple-layer ARC

Bare Si

Plans towards TDR



	2023	2024	2025	2026	2027
Design	 Performance/ optimization studies Mechanical structure design 	Mechanical structure designIntegration	Prototype modules	Engineering modules	Engineering modules
Aerogel	Optical and mechancial studies	Optical and mechancial studies	Integration and mechanics	Integration and mechanics	
D-SiPM	 Test available devices photod. module cooling 	 Characterization of test structures 1st submission photod. module cooling 	 Characterization of D-SiPM prototype 2nd submission photod. module Cooling 	 Validation of D- SiPM cooling integration 	TDR